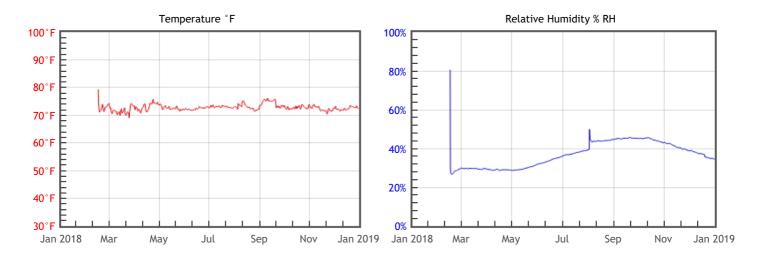
SPC Exhibit-Center

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Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	OK TWPI = 47	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity
Mechanical Damage Physical damage to hygroscopic materials	OK % DC = 0.7 % EMC min = 6 % EMC max = 8.4	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 8.4	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

Graphs



Statistics

Temperature		Relative H	Relative Humidity		Dew Point	
T°F Mean	72.7	%RH Mean	35	DP°F Mean	43	
T°F Median	72.6	%RH Median	33	DP°F Median	41.3	
T°F Stdev	1.1	%RH Stdev	6	DP°F Stdev	4.8	
T°F Min	68.9	%RH Min	26	DP°F Min	33.9	
T°F Max	79.3	%RH Max	81	DP°F Max	72.8	
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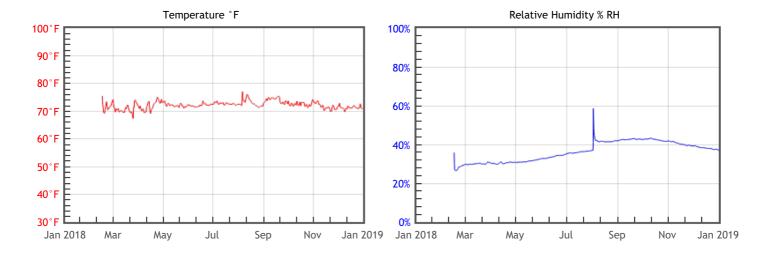
SPC Exhibit-Entrance

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Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	OK TWPI = 49	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity
Mechanical Damage Physical damage to hygroscopic materials	OK % DC = 0.59 % EMC min = 6 % EMC max = 8.1	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 8.1	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

Graphs



Statistics

Temperature		Relative Humidity		Dew Point	
T°F Mean	72.1	%RH Mean	35	DP°F Mean	42.6
T°F Median	72.1	%RH Median	33	DP°F Median	41.6
T°F Stdev	1.4	%RH Stdev	5	DP°F Stdev	4.3
T°F Min	67.4	%RH Min	26	DP°F Min	32.3
T°F Max	77.8	%RH Max	58	DP°F Max	57.7

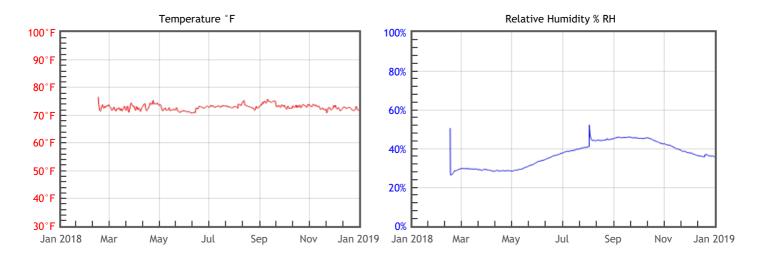
SPC Exhibit-Sound Dome

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Preservation Environment Evaluation

Type of Decay	Risks & Metrics	Evaluation & General Comments
Natural Aging Chemical decay of organic materials	OK TWPI = 46	Generally OK, but fast decaying organic materials such as acidic paper, color photographs and cellulosic plastics will be at elevated risk due to the cumulative effects of temperature and humidity
Mechanical Damage Physical damage to hygroscopic materials	OK % DC = 0.74 % EMC min = 6 % EMC max = 8.6	Generally OK, but sensitive or fast responding hygroscopic materials such as paintings, rare books, vellum manuscripts or musical instruments will be at elevated risk of physical damage due to fluctuations of humidity.
Mold Risk Mold growth in area or on collection objects	GOOD MRF = 0	Minimal risk of mold growth.
Metal Corrosion Corrosion of metal components or objects	OK % EMC max = 8.6	Generally OK, but archeological or salt-encrusted metals may corrode due to extended periods of moderately high levels of humidity.

Graphs



Statistics

Temperature		Relative Humidity		Dew Point	
T°F Mean	72.8	%RH Mean	35	DP°F Mean	43.3
T°F Median	72.8	%RH Median	34	DP°F Median	41.5
T°F Stdev	1	%RH Stdev	6	DP°F Stdev	4.9
T°F Min	69.8	%RH Min	26	DP°F Min	34.3
T°F Max	77.1	%RH Max	52	DP°F Max	56.8